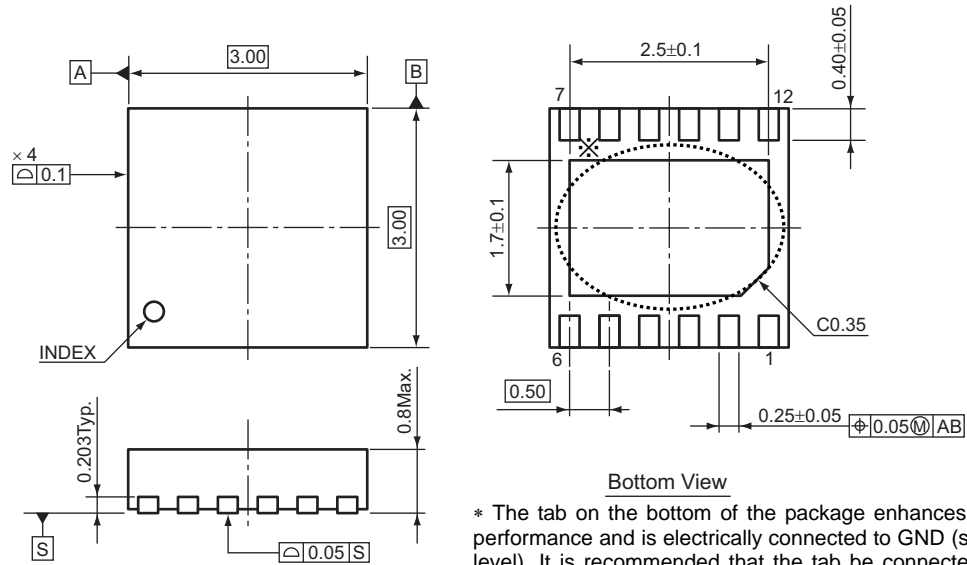


• DFN3030-12

Unit: mm

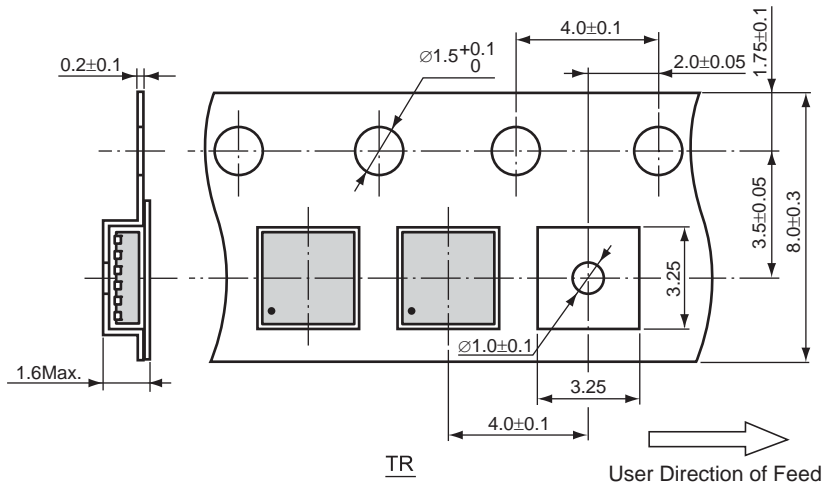
PACKAGE DIMENSIONS



Bottom View

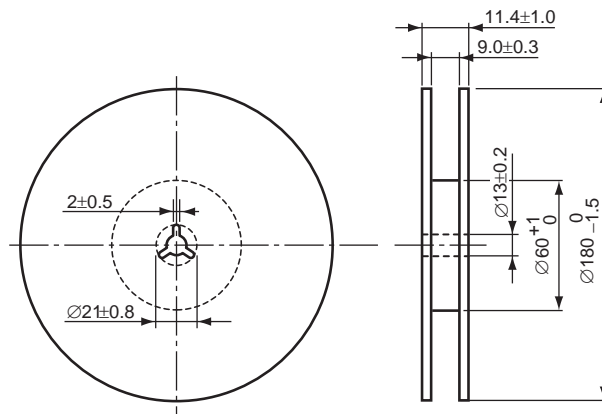
* The tab on the bottom of the package enhances thermal performance and is electrically connected to GND (substrate level). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left floating.

TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

1 reel = 3,000 pcs



POWER DISSIPATION (DFN3030-12)

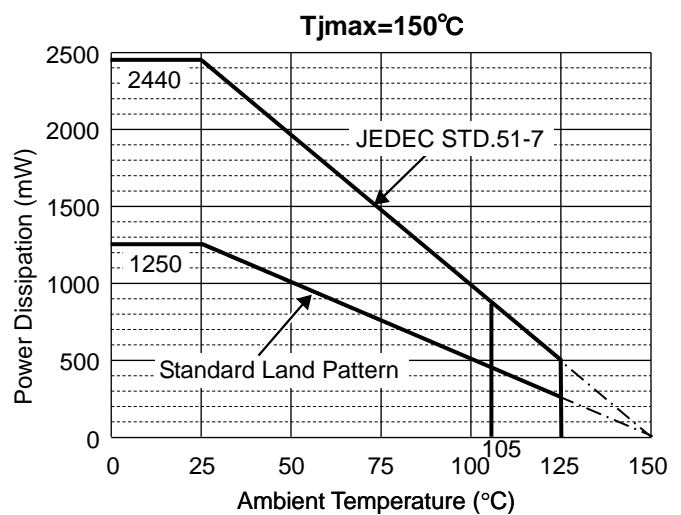
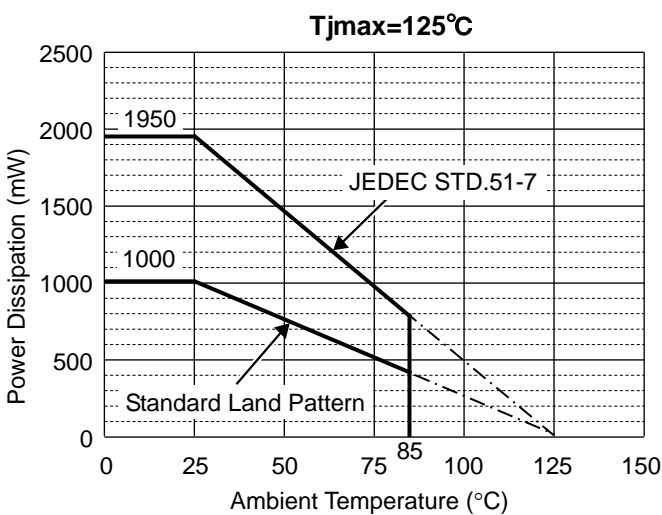
Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Test Land Pattern	JEDEC STD. 51-7 Test Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)	Glass cloth epoxy plastic (Four-layers)
Board Dimensions	40mm x 40mm x 1.6mm	76.2mm x 114.3mm x 1.6mm
Copper Ratio	Top side: Approx. 50%, Back side: Approx. 50%	Top side, Back side : 60mmx60mm, Approx. 10% 2nd, 3rd Layer : 74.2mmx74.2mm, Approx. 100%
Through-holes	ϕ 0.54mm x 32pcs	ϕ 0.85mm x 64pcs * The land pattern of Tab (Heat spreader), the inner layers and the backside pattern are connected by 0.3mm through-hole.

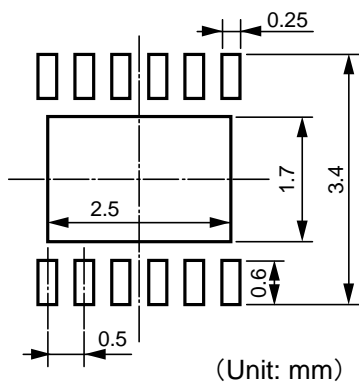
Measurement Result ($T_a=25^\circ\text{C}$)

	Standard Test Land Pattern	JEDEC STD. 51-7 Test Land Pattern
Power Dissipation	1000mW ($T_{jmax}=125^\circ\text{C}$) 1250mW ($T_{jmax}=150^\circ\text{C}$)	1950mW ($T_{jmax}=125^\circ\text{C}$) 2440mW ($T_{jmax}=150^\circ\text{C}$)
Thermal Resistance	$\theta_{ja}=100^\circ\text{C/W}$	$\theta_{ja}=51.2^\circ\text{C/W}$
	$\theta_{jc}=18^\circ\text{C/W}$	$\theta_{jc}=5.9^\circ\text{C/W}$

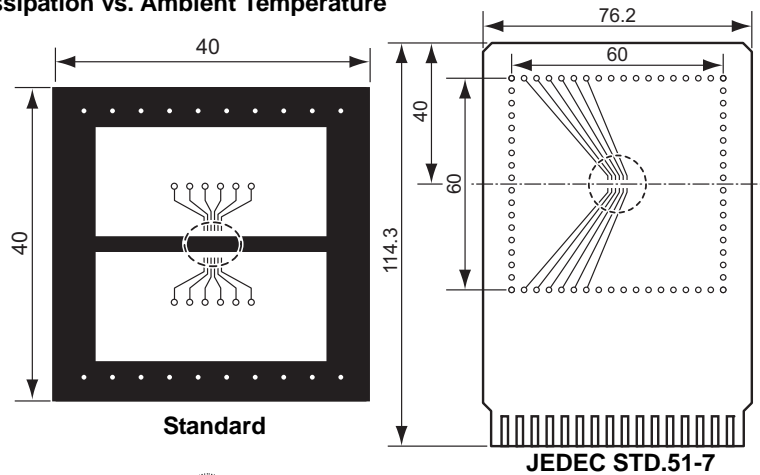


Power Dissipation vs. Ambient Temperature

RECOMMENDED LAND PATTERN



(Unit: mm)



○ IC Mount Area (Unit: mm)
Measurement Board Pattern